

C8829A

Conductor

Description

C8829A is a low firing silver conductor paste. It exhibits excellent solderability on a wide variety of substrates including aluminum, anodized aluminum, alumina and soda lime glass.

Key Features

- Low firing temperature
- Excellent solderability
- Low resistivity Au and Al wire bondable



This picture does not show the packaging of C8829A and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Conductivity	≤ 3.5 milliohms/square at 12 um fired film thickness
Viscosity	150 -200 Kcps Brookfield HBTSC4-14 spindle, 6R utility cup at 10 rpm, 25 °C
Alloy Ratio	100
Metal	Ag

Recommended Processing Guide

Process Temperature (TDS)	490-550 °C peak temperature. Dwell time of 5-8 minutes.
Film Thickness	6-10 um

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